

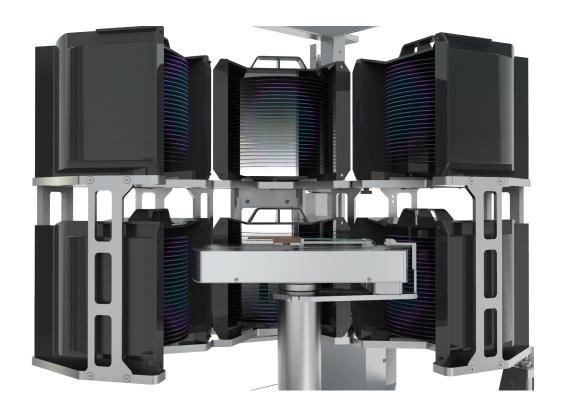
Vertical

Furnaces Reference Guide

Configurable Vertical Furnace for R&D or Production

- Two-boat rotating system
- Automatic wafer handling system for loading wafers from SMIF or FOUP closed pods
- Quartz or SiC boats can be used
- Highly tailored state of the art modular control system, in house designed and manufactured
- 10,4" high-res touchscreen for operator interface
- Special automatic loading system which allows loading wafers from open cassettes and provides an exceptionally small footprint





Processes

Atmospheric

- Diffusion (drive-in) high temperature processes
- Doping from solid, liquid and gaseous dopant sources e.g. BBr₃, B₂H₆, POCL₃, PH₃, BN
- | Dry Oxide
- Pyrogenic Wet Oxide with External Burning System
- Various thermal processing e.g. annealing, sintering

LPCVD

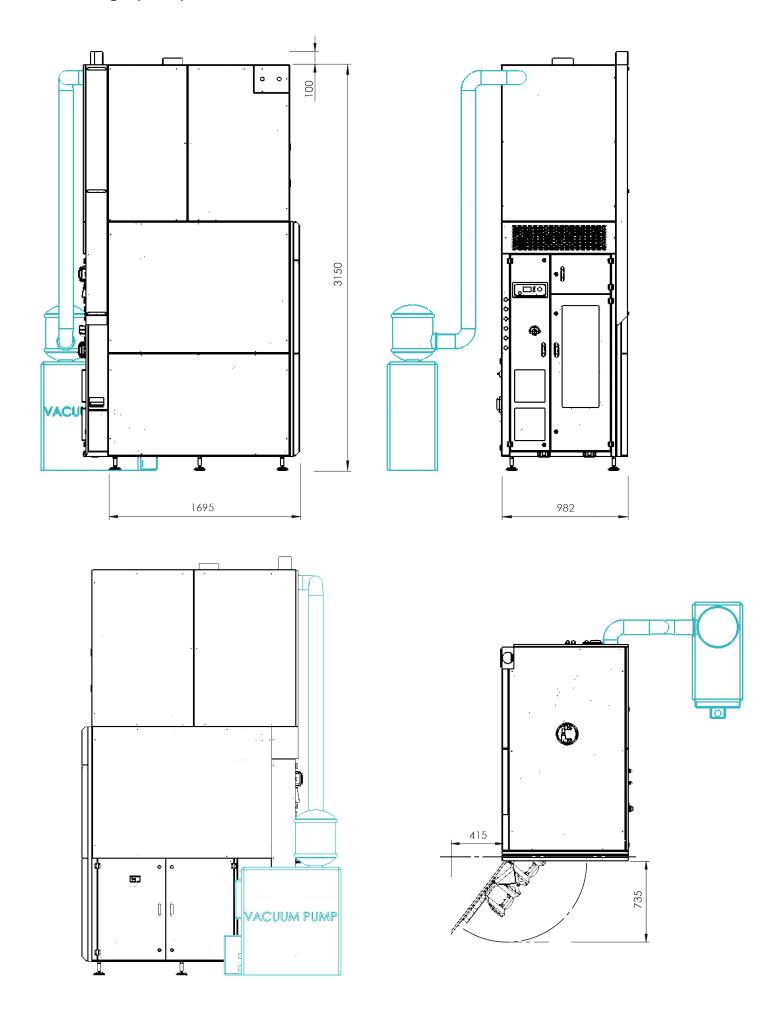
- Silicon nitride / low stress nitride
- Oxynitride
- High temperature oxide (HTO)
- Low temperature oxide (LTO)
- Polysilicon, both with tilt and flat temperature profile
- Doped polysilicon
- I TEOS oxide

DCE or HCl optional for all processes

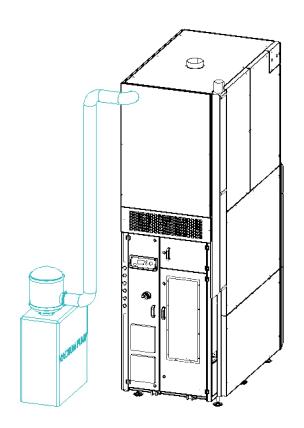
Technical Data

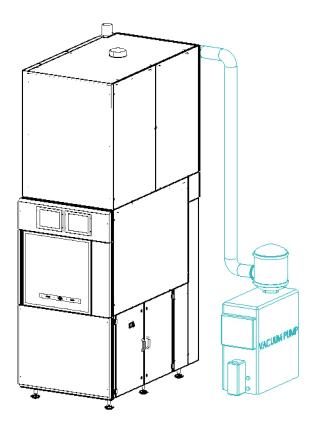
Wafer size (mm)	100, 150, 200, 300 or any custom size
Wafer load	25 – 150 wafers/batch
Heating system	3 or 5 zone
Flat zone	Up to 600 mm (24")
Process temperature	200°C to 1230°C, ± 0.5 °C across flat zone
Power consumption	22kW - 30kW
Power supply (adapted to power grid of destination country)	3-phase, 400 or 480VAC, 40 – 100A, 50 or 60Hz
Clean dry air	70 – 110 psig (4,8 to 7,6 bar)
Cooling water	10 – 15 LPM
Exhaust	170m³/h

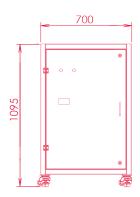
Drawings (mm)

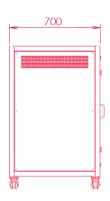


Drawings (mm)









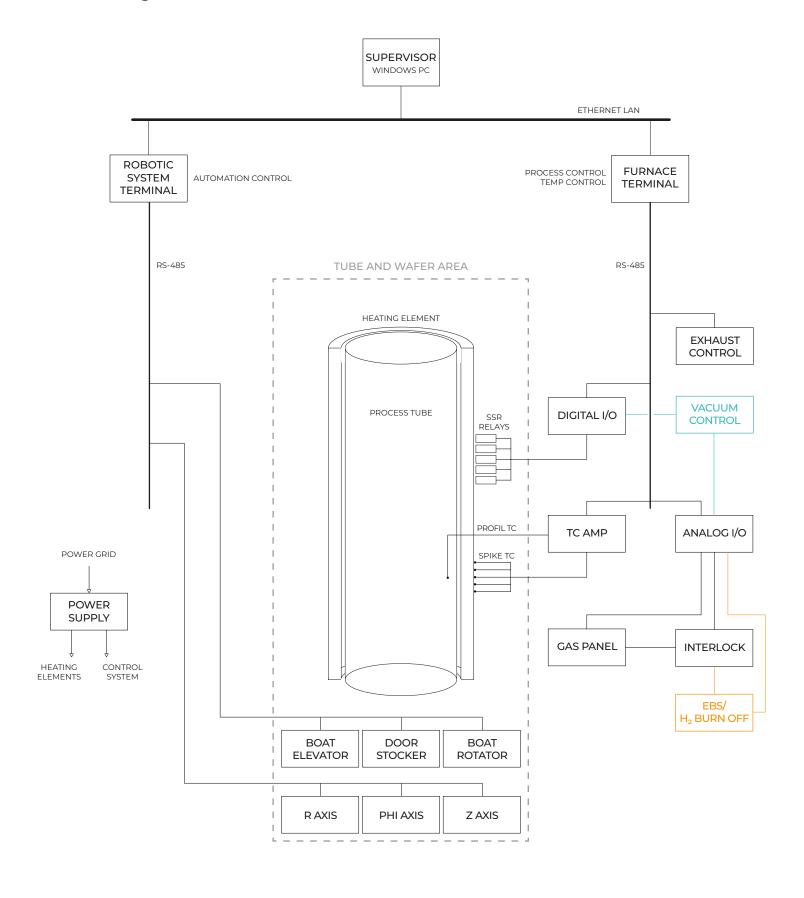


Atmospheric variant

LPCVD variant

External power supply variant

Block diagram

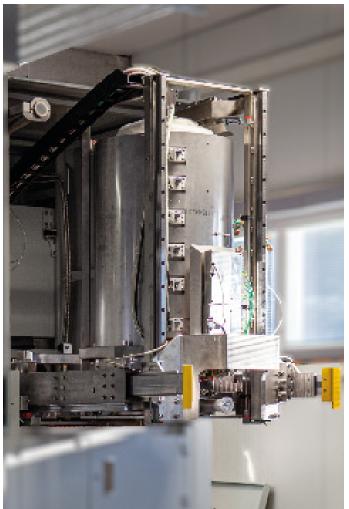


Optional External Burn System or Hydrogen Burn Off

Optional LPCVD Vacuum Assembly













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